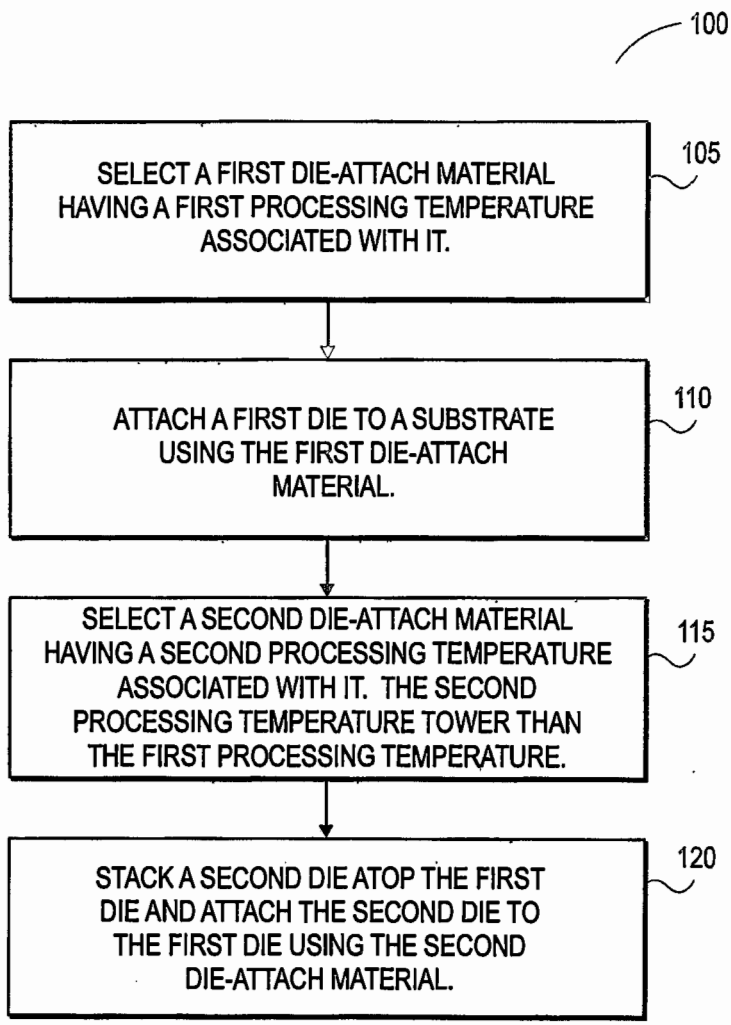

100
SELECT A FIRST DIE-ATTACH MATERIAL HAVING A FIRST PROCESSING TEMPERATURE ASSOCIATED WITH IT.
105
ATTACH A FIRST DIE TO A SUBSTRATE USING THE FIRST DIE-ATTACH MATERIAL.
110
SELECT A SECOND DIE-ATTACH MATERIAL HAVING A SECOND PROCESSING TEMPERATURE ASSOCIATED WITH IT. THE SECOND PROCESSING TEMPERATURE TOWER THAN THE FIRST PROCESSING TEMPERATURE.
115
STACK A SECOND DIE ATOP THE FIRST DIE AND ATTACH THE SECOND DIE TO THE FIRST DIE USING THE SECOND DIE-ATTACH MATERIAL.
120

FIG. 1

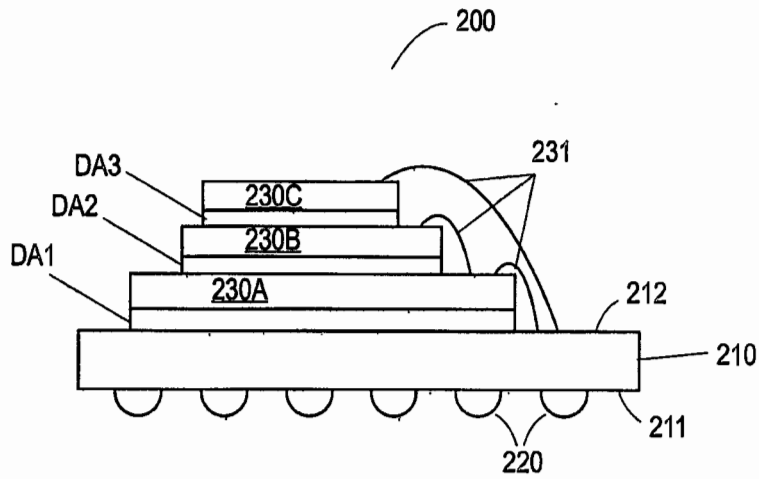


FIG. 2

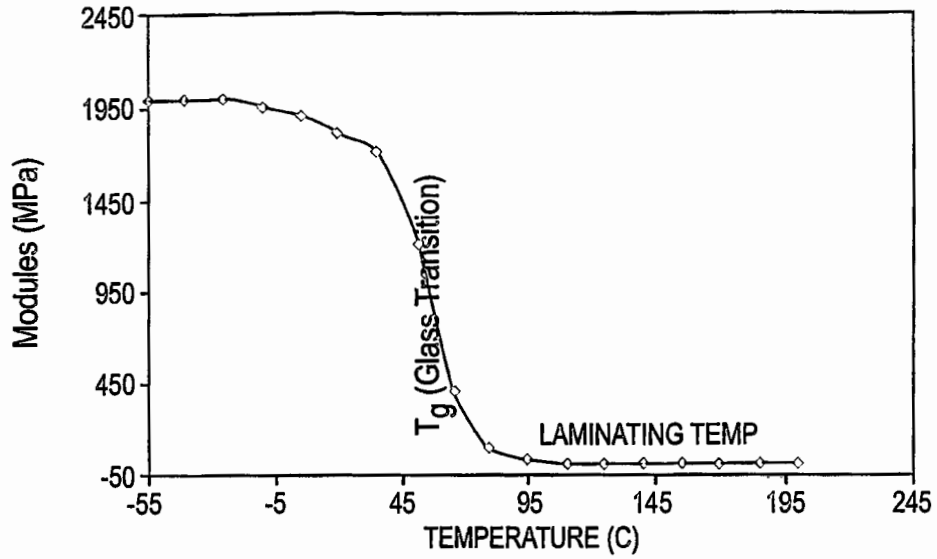

2450
1950
1450
950
450
-50
Modules (MPa)
Tg (Glass Transition)
LAMINATING TEMP
-55
-5
45
95
145
195
245
TEMPERATURE (C)

FIG. 3A

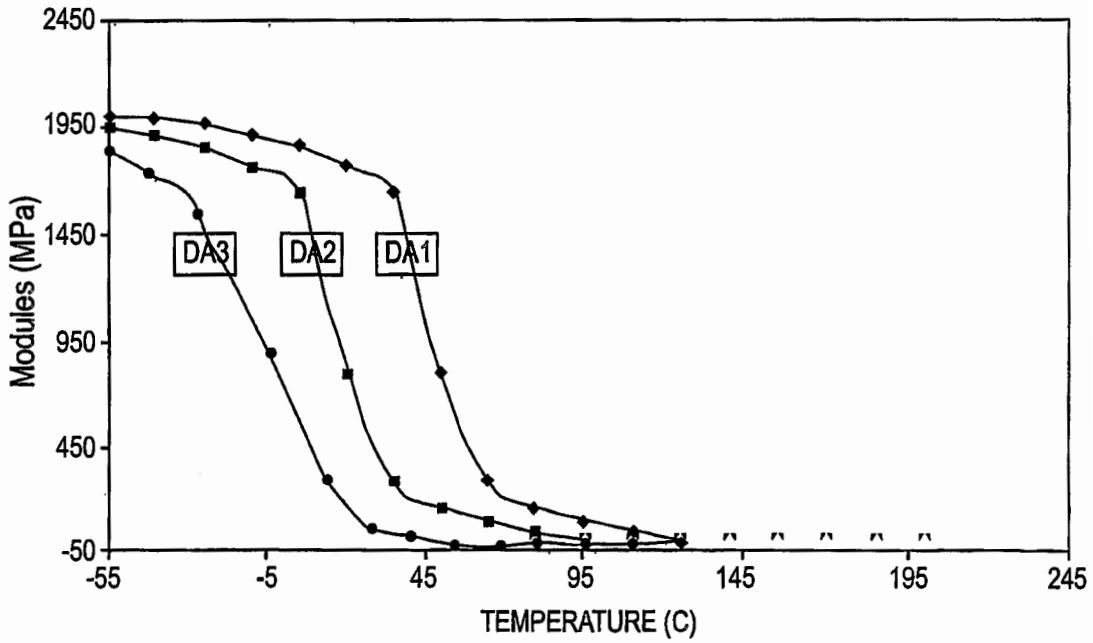

2450
1950
1450
950
450
-50
Modules (MPa)
DA3
DA2
DA1
-55
-5
45
95
145
195
245
TEMPERATURE (C)

FIG. 3B